1. Title of the Invention

Method for forming stereoscopic circuit

2. Claim

A method for forming a stereoscopic circuit comprising:

(a) forming a first conductive thin film on a substrate;

(b) forming a first dielectric layer on the first conductive thin film in a state wherein a first, second, and third regions of the first conductive thin film are exposed, the second and third regions being opposed to each other across the first region;

(c) coating the first, second, and third regions with conductive materials to form a first, second, and third conductive layer with the same thickness as the first dielectric layer;

(d) forming a second dielectric layer on the first, second, and third conductive layers and the first dielectric layer in a state wherein a fourth region of the second conductive layer and a fifth region of the third conductive layer are exposed;

(e) coating the fourth and fifth regions with conductive materials to form a fourth and fifth conductive layers with the same thickness as the second dielectric layer;

(f) forming a second conductive thin film on the fourth and fifth conductive layers and the second dielectric layer;

(g) forming a third dielectric layer on the second conductive thin film in a state wherein a sixth, seventh, and eighth regions are exposed, the sixth and seventh regions being faced with whole or part of the fourth and fifth conductive layers and the eighth region being placed between the sixth and seventh regions;

(h) coating the sixth, seventh, and eighth regions with conductive materials to form a sixth conductive layer;

(i) etching the first, second, and third dielectric layers and the first and second conductive thin films except the first, second, third, sixth, and seventh conductive regions; and

(j) forming a first circuit consisting of the first conductive layer and a second circuit consisting of the second, third, sixth, and seventh regions in such a manner that the first and the second circuits are intersected with each other.